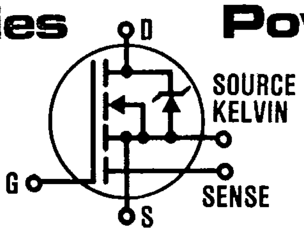
T-39-11
Data Sheet No. PD-9.455C

INTERNATIONAL RECTIFIER IOR

REPETITIVE AVALANCHE AND dv/dt RATED*

HEXSense™— Current Sense C Series Power MOSFET

IRC830 IRC832



N-CHANNEL

500 Volt, 1.5 Ohm Current Sense Plastic Package Similar to TO-220

The HEXSense® "C" Series Power MOSFETs incorporate a current sensing feature, obtained by isolating a few cells in its structure. In addition to the well established characteristics of the HEXFETs, they provide an accurate fraction of the drain current as a feedback parameters for control and/or protection.

Fields of applications include: current mode motor control; power supplies using flyback or push pull topology; uninterruptible power systems; instrumentation; solid state relays; CRT deflection, solenoid and lamp drive circuits.

The HEXFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry and unique processing of the HEXFET design achieve very low on-state resistance combined with high transconductance and great device ruggedness.

Product Summary

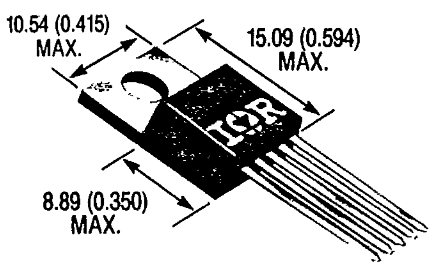
Part Number	BV_{DSS}	$R_{DS(on)}$	I_D
IRC830	500V	1.5Ω	4.5A
IRC832	500V	2.0Ω	4.0A

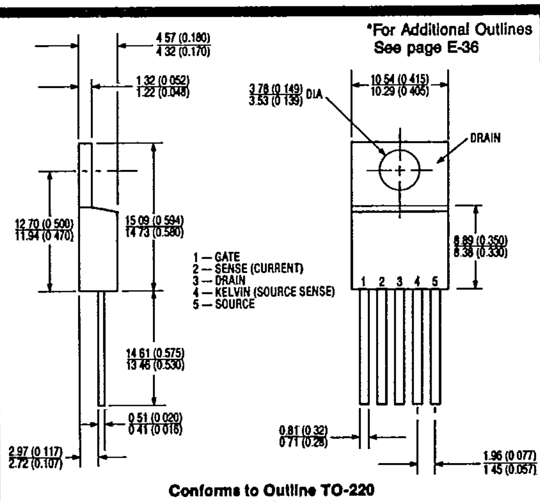
Features:

- +2 1/2 Sensing Accuracy
- Repetitive Avalanche Ratings
- Dynamic dv/dt Rating
- Simple Drive Requirements

CURRENT SENSING DEVICES

CASE STYLE AND DIMENSIONS





Conforms to Outline TO-220
(IR H-7)
Dimensions in Millimeters and (Inches)

This data sheet applies to product with batch codes that begin with a digit, ie. 2A3B

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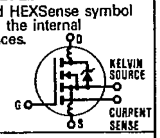
Absolute Maximum Ratings

	Parameter	IRC830	IRC832	Units
I_D @ T_C = 25°C	Continuous Drain Current	4.5	4.0	A
I_D @ T_C = 100°C	Continuous Drain Current	3.0	2.5	A
I_{DM}	Pulsed Drain Current ①	15	13	A
P_D @ T_C = 25°C	Max. Power Dissipation	74		W
	Linear Derating Factor	0.59		W/K ⑤
V_{GS}	Gate-to-Source Voltage	±20		V
E_{AS}	Single Pulse Avalanche Energy ②	280 (See Fig. 14)		mJ
I_{AR}	Avalanche Current ① (Repetitive or Non-Repetitive)	4.5 (See E_{AR})		A
E_{AR}	Repetitive Avalanche Energy ①	7.4 (See I_{AR})		mJ
dv/dt	Peak Diode Recovery dv/dt ③	3.5 (See Fig. 17)		V/ns
T_J T_{STG}	Operating Junction Storage Temperature Range	−55 to 150		°C
	Lead Temperature	300 (0.063 in. (1.6mm) from case for 10s)		°C

Electrical Characteristics @ T_J = 25°C (Unless Otherwise Specified)

	Parameter	Type	Min.	Typ.	Max.	Units	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	ALL	500	—	—	V	V_{GS} = 0V, I_D = 250 μA
$R_{DS(on)}$	Static Drain-to-Source On-State Resistance ④	IRC830	—	1.4	1.5	Ω	V_{GS} = 10V, I_D = 2.5A
		IRC832	—	1.5	2.0		
$I_{D(on)}$	On-State Drain Current ④	IRC830	4.3	—	—	A	V_{DS} > $I_{D(on)}$ X $R_{DS(on)}$ Max. V_{GS} = 10V
		IRC832	3.7				
$V_{GS(th)}$	Gate Threshold Voltage	ALL	2.0	—	4.0	V	V_{DS} = V_{GS}, I_D = 250μA
g_{fs}	Forward Transconductance ④	ALL	2.7	4.1	—	S (℧)	V_{DS} = 2 x V_{GS}, I_{DS} = 2.5A
I_{DSS}	Zero Gate Voltage Drain Current	ALL	—	—	250	μA	V_{DS} = Max. Rating, V_{GS} = 0V
			—	—	1000		V_{DS} = 0.8 x Max. Rating V_{GS} = 0V, T_J = 125°C
I_{GSS}	Gate-to-Source Leakage Forward	ALL	—	—	500	nA	V_{GS} = 20V
I_{GSS}	Gate-to-Source Leakage Reverse	ALL	—	—	−500	nA	V_{GS} = −20V
Q_g	Total Gate Charge	ALL	—	21	32	nC	V_{GS} = 10V, I_D = 4.5A V_{DS} = 0.8 x Max. Rating See Fig. 16 (Independent of operating temperature)
Q_{gs}	Gate-to-Source Charge	ALL	—	3.2	4.8	nC	
Q_{gd}	Gate-to-Drain ("Miller") Charge	ALL	—	11	17	nC	
$t_{d(on)}$	Turn-On Delay Time	ALL	—	11	17	ns	V_{DD} = 250V, I_D ≈ 4.5A, R_G = 12Ω R_D = 57Ω See Fig. 15 (Independent of operating temperature)
t_r	Rise Time	ALL	—	15	23	ns	
$t_{d(off)}$	Turn-Off Delay Time	ALL	—	35	53	ns	
t_f	Fall Time	ALL	—	15	23	ns	
L_D	Internal Drain Inductance	ALL	—	4.5	—	nH	Measured from the drain lead, 6mm (0.25 in.) from package to center of die. / Modified HEXSense symbol showing the internal inductances.
L_S	Internal Source Inductance	ALL	—	7.5	—	nH	Measured from the source lead, 6mm (0.25 in.) from package to source bonding pad. 
C_{iss}	Input Capacitance	ALL	—	610	—	pF	V_{GS} = 0V, V_{DS} = 25V f = 1.0 MHz See Fig. 10
C_{oss}	Output Capacitance	ALL	—	91	—	pF	
C_{rss}	Reverse Transfer Capacitance	ALL	—	18	—	pF	

IRC830, IRC832 Devices

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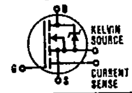
Source-Drain Diode Ratings and Characteristics

	Parameter	Type	Min.	Typ.	Max.	Units	Test Conditions
I_S	Continuous Source Current (Body Diode)	ALL	–	–	4.3	A	Modified HEXSense symbol showing the integral Reverse p-n junction rectifier. 
I_{SM}	Pulsed Source Current (Body Diode) ①	ALL	–	–	15	A	
V_{SD}	Diode Forward Voltage ④	ALL	–	–	1.6	V	T_J = 25°C, I_S = 4.4A, V_{GS} = 0V
t_{rr}	Reverse Recovery Time	ALL	190	410	940	ns	T_J = 25°C, I_F = 4.4A, di/dt = 100 A/μs
Q_{RR}	Reverse Recovery Charge	ALL	0.91	2.0	4.7	μC	
t_{on}	Forward Turn-On Time	ALL	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $L_S + L_D$.				

Current Sense Characteristics @ T_J = 25°C (Unless Otherwise Noted)

	Parameter	Type	Min.	Typ.	Max.	Units	Test Conditions
r	Current Sensing Ratio	ALL	1480	1520	1560	–	I_D = 4.4A V_{GSS} = 10V
C_{oss}	Output Capacitance of Sensing Cells	ALL	–	9.0	–	pF	V_{GS} = 0V, V_{DS} = 25V, F = 1 MHz

Thermal Resistance

R_{thJC}	Junction-to-Case	ALL	–	–	1.7	K/W ⑤	
R_{thJS}	Case-to-Sink	ALL	–	0.50	–	K/W ⑤	Mounting surface flat, smooth, and greased
R_{thJA}	Junction-to-Ambient	ALL	–	–	80	K/W ⑤	Typical socket mount

① Repetitive Rating; Pulse width limited by maximum junction temperature (see figure 5) Refer to current HEXFET reliability report

② @ V_{DD} = 56V, Starting T_J = 25°C, L = 25 mH, R_G = 25Ω, Peak I_L = 4.6A

③ I_{SD} ≤ 4.5A, di/dt ≤ 75A/μs, V_{DD} ≤ BV_{DSS}, T_J ≤ 150°C Suggested R_G = 12Ω

④ Pulse width ≤ 300 μs; Duty Cycle ≤ 2%

⑤ K/W = °C/W W/K = W/°C

CURRENT SENSING DEVICES

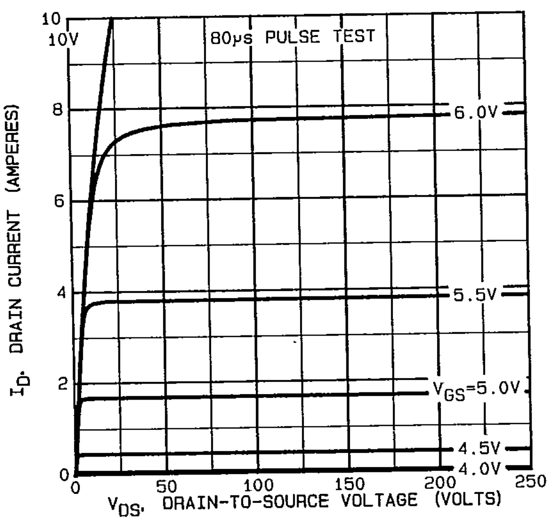


Fig. 1 — Typical Output Characteristics

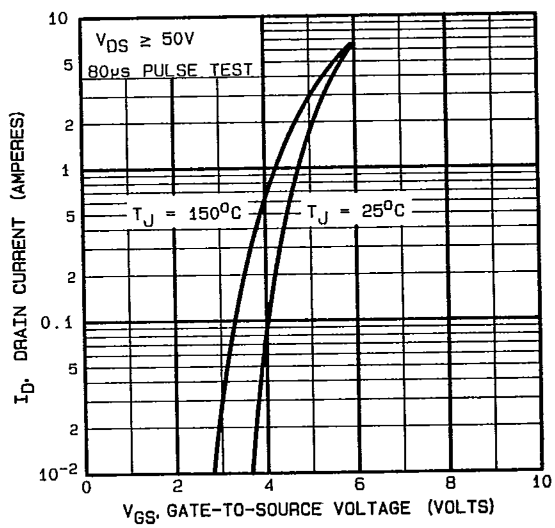


Fig. 2 — Typical Transfer Characteristics

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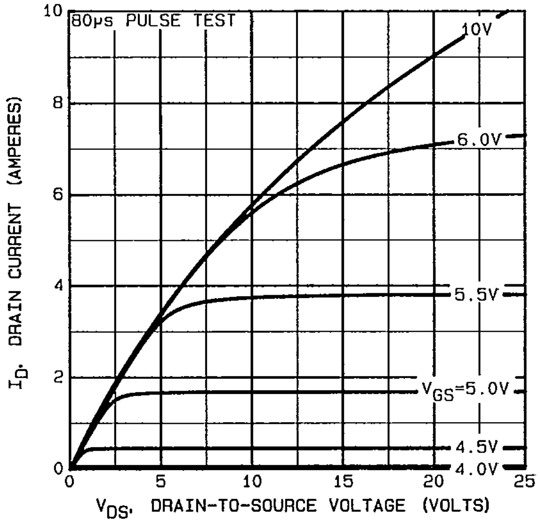

Fig. 3 — Typical Saturation Characteristics

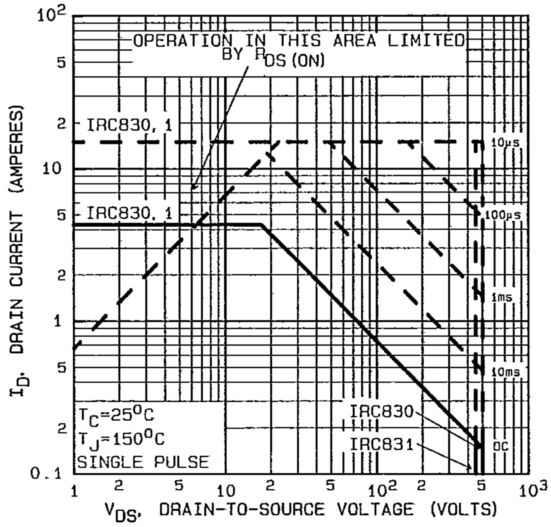

Fig. 4 — Maximum Safe Operating Area

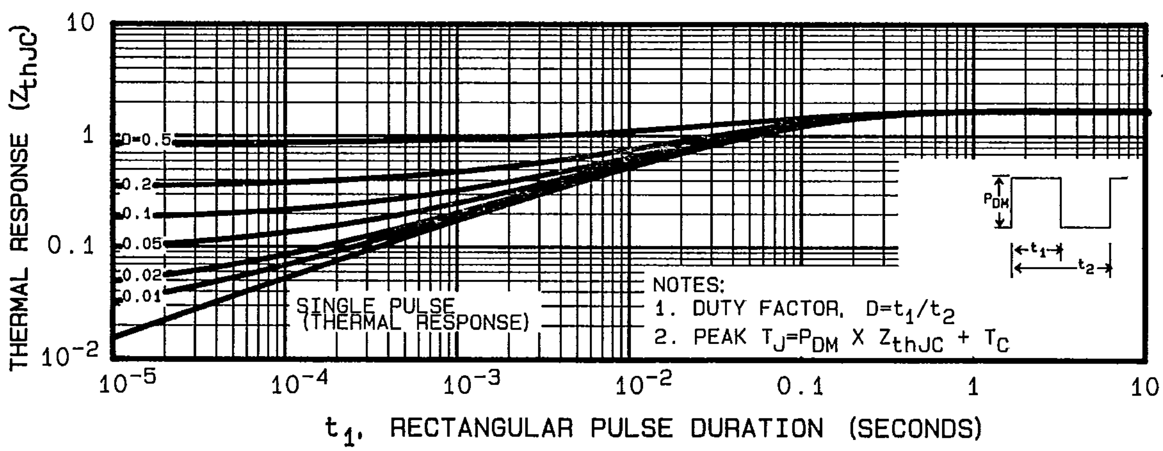

Fig. 5 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

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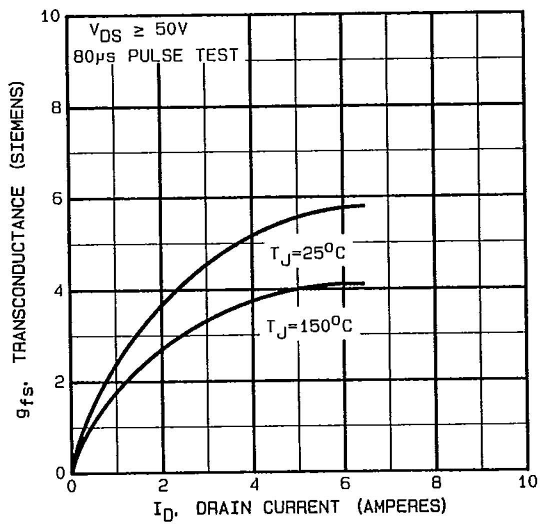

Fig. 6 — Typical Transconductance Vs. Drain Current

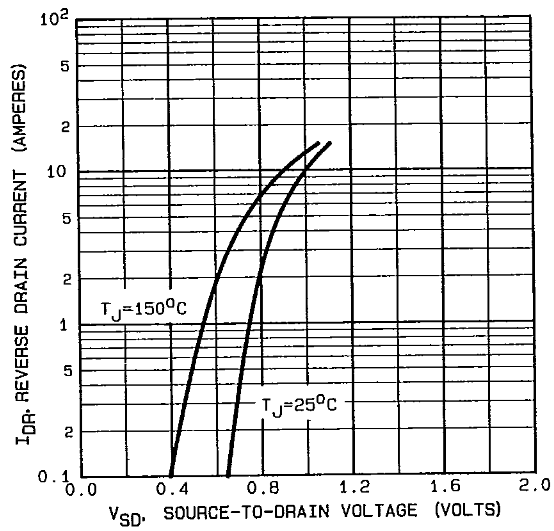

Fig. 7 — Typical Source-Drain Diode Forward Voltage

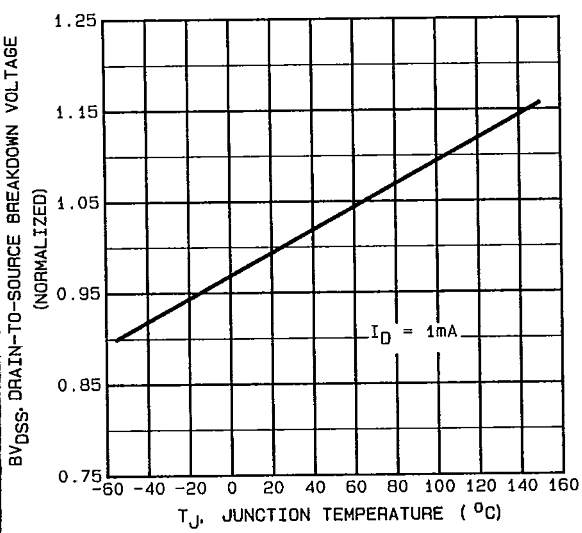

Fig. 8 — Breakdown Voltage Vs. Temperature

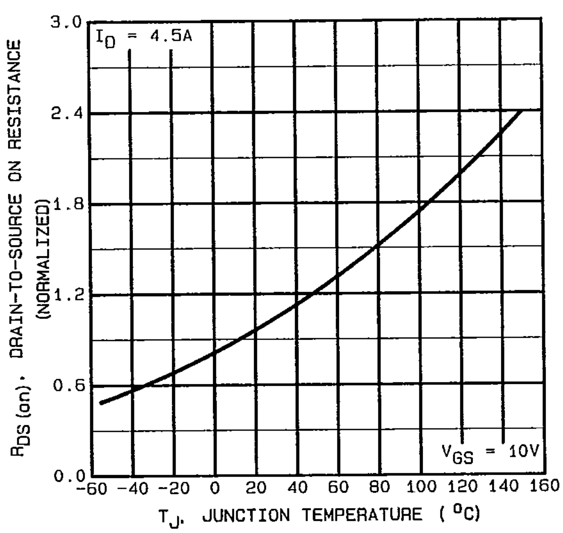

Fig. 9 — Normalized On-Resistance Vs. Temperature

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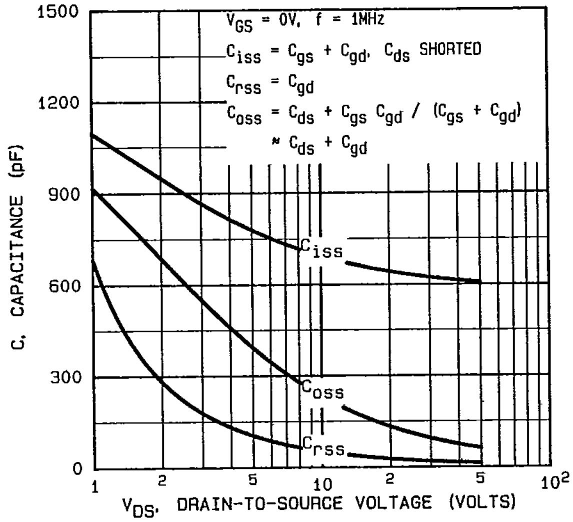


Fig. 10 — Typical Capacitance Vs. Drain-to-Source Voltage

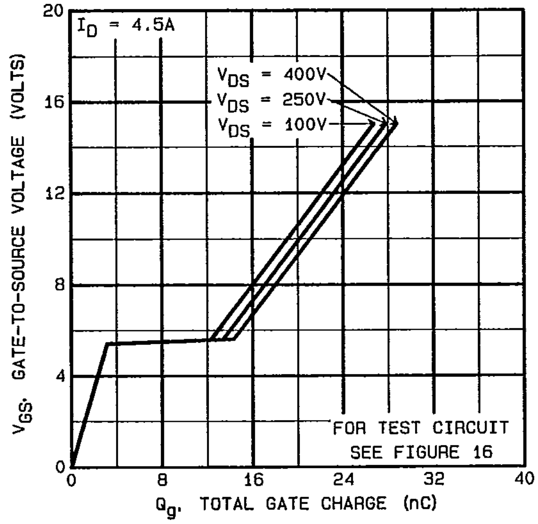


Fig. 11 — Typical Gate Charge Vs. Gate-to-Source Voltage

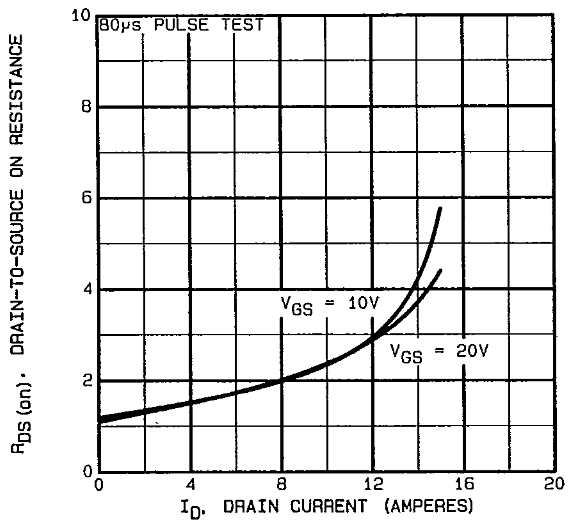


Fig. 12 — Typical On-Resistance Vs. Drain Current

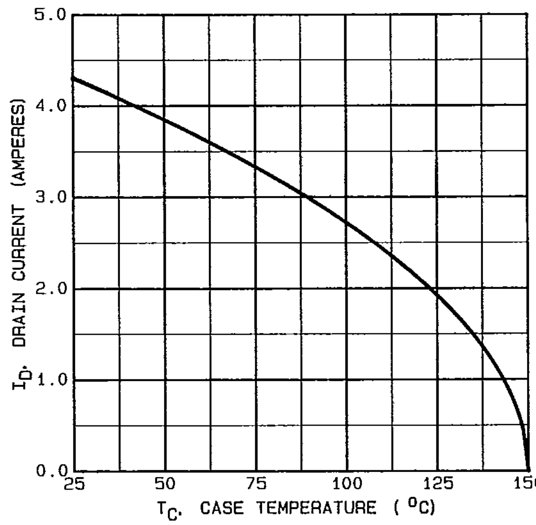


Fig. 13 — Maximum Drain Current Vs. Case Temperature

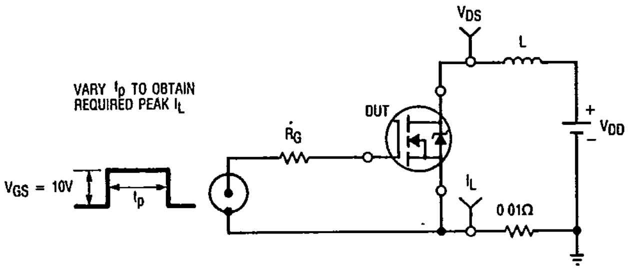


Fig. 14a — Unclamped Inductive Test Circuit

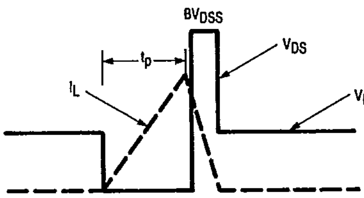


Fig. 14b — Unclamped Inductive Waveforms

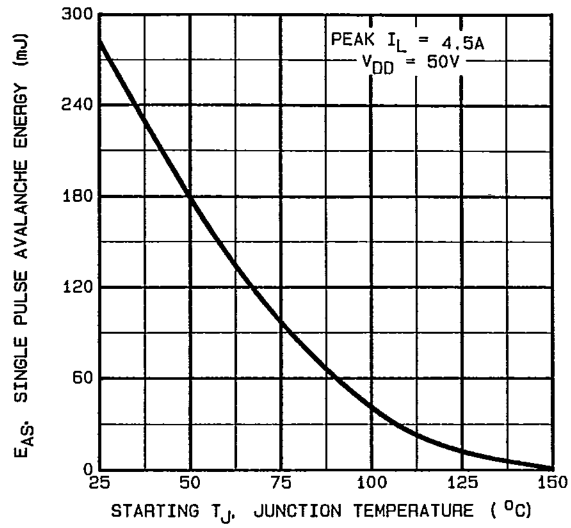


Fig. 14c — Maximum Avalanche Energy Vs. Starting Junction Temperature

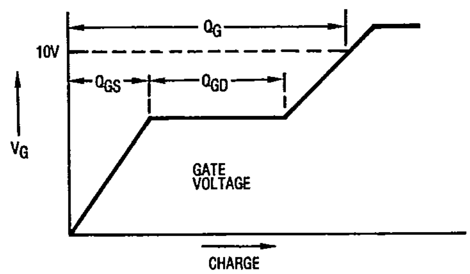


Fig. 16a — Basic Gate Charge Waveform

CURRENT SENSING DEVICES

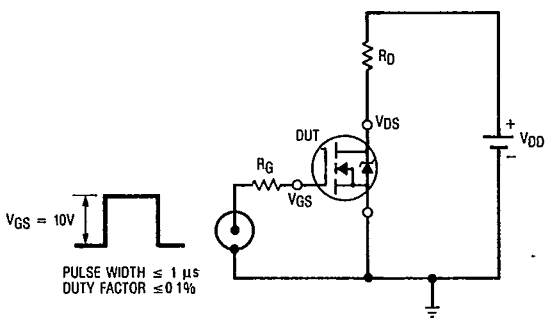


Fig. 15a — Switching Time Test Circuit

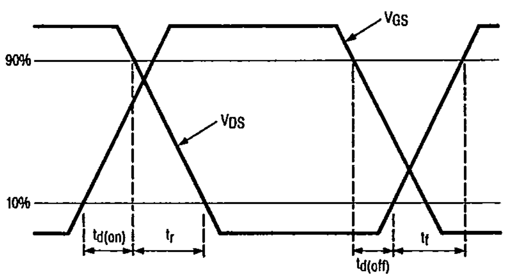


Fig. 15b — Switching Time Waveforms

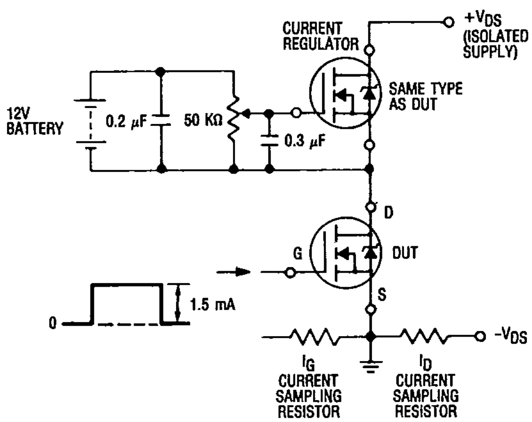


Fig. 16b — Gate Charge Test Circuit

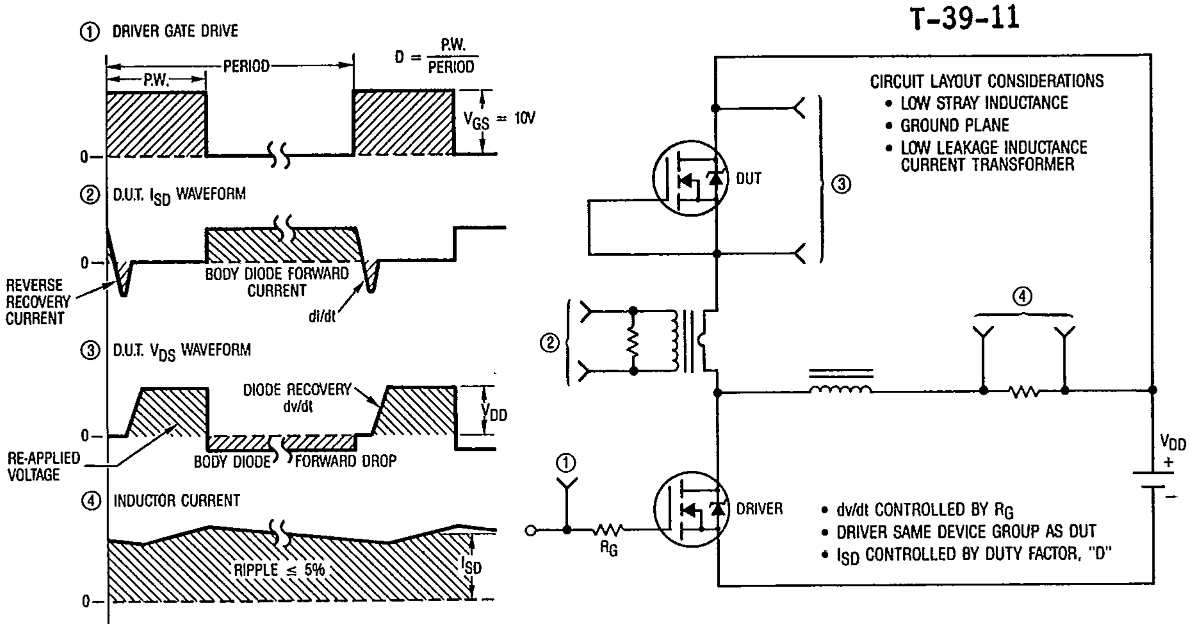


Fig. 17 — Peak Diode Recovery dv/dt Test Circuit

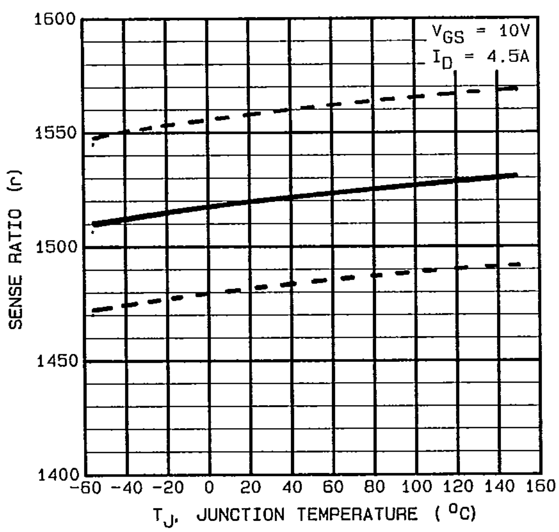


Fig. 18 — HEXSense Ratio Vs. Junction Temperature

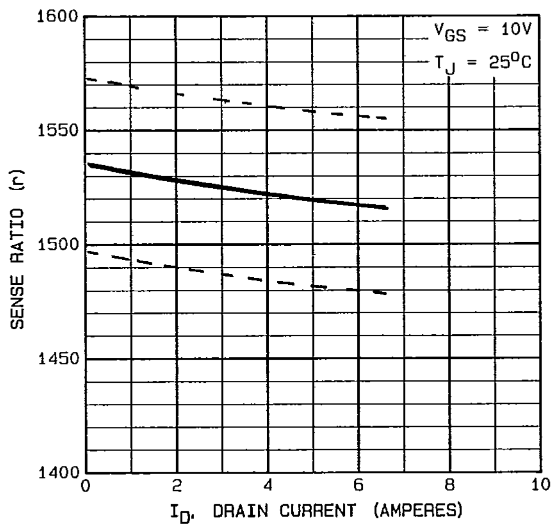


Fig.19 — HEXSense Ratio Vs. Drain Current

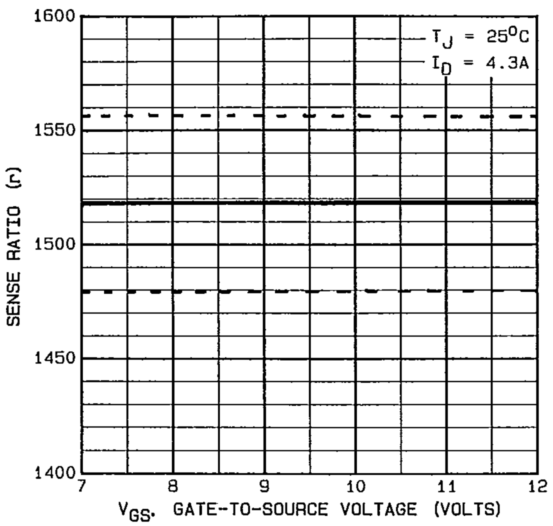


Fig. 20 — HEXSense Ratio Vs. Gate Voltage

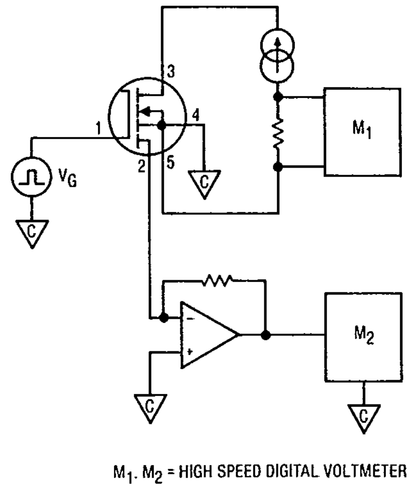


Fig. 21 — HEXSense Ratio Test Circuit

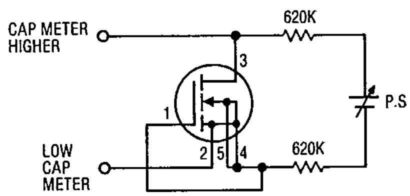


Fig. 22 — Output Capacitance Test Circuit for HEXSense Only

CURRENT SENSING DEVICES

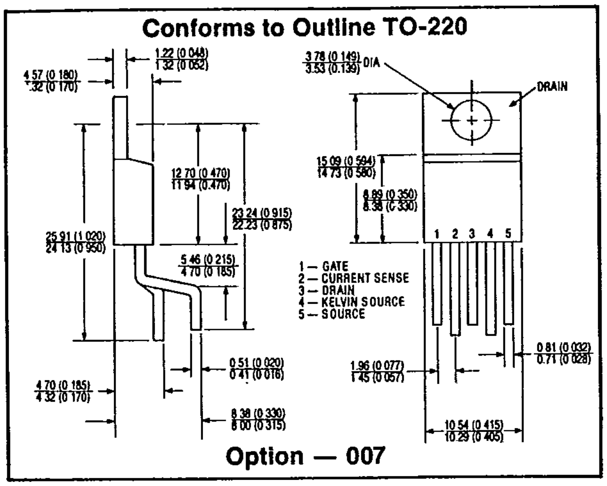


Fig. 23 — HEXSense Case Style (H-8)

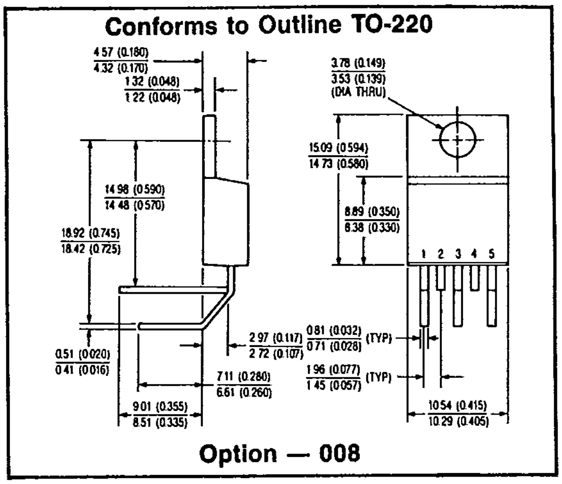
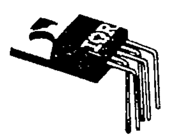


Fig. 24 — HEXSense Case Style (H-9)

Dimensions in Millimeters and (Inches)

ORDERING INFORMATION

Part Number	Case Style	
IRC830	IR H-7	
IRC832		
IRC830-007	IR H-8	
IRC832-007		
IRC830-008	IR H-9	
IRC832-008		

Other lead formings are available upon request.